

Notice of References Cited	Application/Control No. 09/851,313		Applicant(s)/Patent Under Reexamination USAMI, TATSUYA	
	Examiner Julio J. Maldonado		Art Unit 2823	Page 1 of 1

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*		Document Number Country Code-Number-Kind Code	Date MM-YYYY	Name	Classification
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*	B	US-6,333,257	12-2001	Aoi, Nobuo	438/626
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	I	US-			
	J	US-			
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	L	US-			
	M	US-			

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NON-PATENT DOCUMENTS

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	U	Wolf et al., Silicon Processing for the VLSI Era, Volume 1, PProcess teachnology, 1986 by Lattice Press, pages 168-174
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*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.